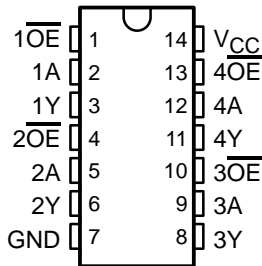


# SN54AHCT125, SN74AHCT125 QUADRUPLE BUS BUFFER GATES WITH 3-STATE OUTPUTS

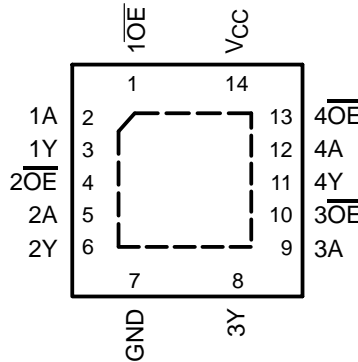
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- Inputs Are TTL-Voltage Compatible
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

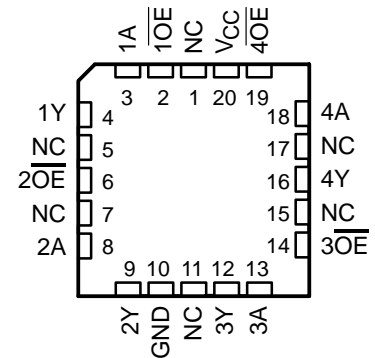
SN54AHCT125 . . . J OR W PACKAGE  
SN74AHCT125 . . . D, DB, DGV, N, NS,  
OR PW PACKAGE  
(TOP VIEW)



SN74AHCT125 . . . RGY PACKAGE  
(TOP VIEW)



SN54AHCT125 . . . FK PACKAGE  
(TOP VIEW)



NC – No internal connection

## description/ordering information

The 'AHCT125 devices are quadruple bus buffer gates featuring independent line drivers with 3-state outputs. Each output is disabled when the associated output-enable ( $\overline{OE}$ ) input is high. When  $\overline{OE}$  is low, the respective gate passes the data from the A input to its Y output.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QFN – RGY	Tape and reel	SN74AHCT125RGYR	HB125
	PDIP – N	Tube	SN74AHCT125N	SN74AHCT125N
	SOIC – D	Tube	SN74AHCT125D	AHCT125
		Tape and reel	SN74AHCT125DR	
	SOP – NS	Tape and reel	SN74AHCT125NSR	AHCT125
	SSOP – DB	Tape and reel	SN74AHCT125DBR	HB125
	TSSOP – PW	Tube	SN74AHCT125PW	HB125
Tape and reel		SN74AHCT125PWR		
	TVSOP – DGV	Tape and reel	SN74AHCT125DGVR	HB125
–55°C to 125°C	CDIP – J	Tube	SNJ54AHCT125J	SNJ54AHCT125J
	CFP – W	Tube	SNJ54AHCT125W	SNJ54AHCT125W
	LCCC – FK	Tube	SNJ54AHCT125FK	SNJ54AHCT125FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS  
INSTRUMENTS**

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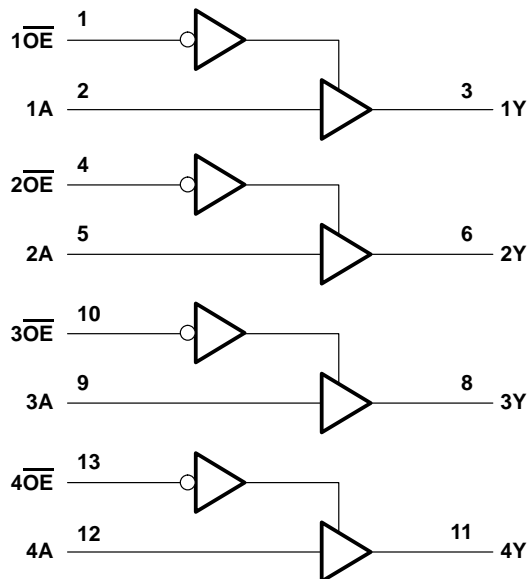
# SN54AHCT125, SN74AHCT125 QUADRUPLE BUS BUFFER GATES WITH 3-STATE OUTPUTS

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FUNCTION TABLE  
(each buffer)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

## logic diagram (positive logic)



Pin numbers shown are for the D, DB, DGV, J, N, NS, PW, RGY, and W packages.

# SN54AHCT125, SN74AHCT125 QUADRUPLE BUS BUFFER GATES WITH 3-STATE OUTPUTS

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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$ .....	–0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1) .....	–0.5 V to 7 V
Output voltage range, $V_O$ (see Note 1) .....	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, $I_{IK}$ ( $V_I < 0$ ) .....	–20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) .....	±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) .....	±25 mA
Continuous current through $V_{CC}$ or GND .....	±50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): D package .....	86°C/W
(see Note 2): DB package .....	96°C/W
(see Note 2): DGV package .....	127°C/W
(see Note 2): N package .....	80°C/W
(see Note 2): NS package .....	76°C/W
(see Note 2): PW package .....	113°C/W
(see Note 3): RGY package .....	47°C/W
Storage temperature range, $T_{stg}$ .....	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
 2. The package thermal impedance is calculated in accordance with JESD 51-7.  
 3. The package thermal impedance is calculated in accordance with JESD 51-5.

## recommended operating conditions (see Note 4)

	SN54AHCT125		SN74AHCT125		UNIT
	MIN	MAX	MIN	MAX	
$V_{CC}$ Supply voltage	4.5	5.5	4.5	5.5	V
$V_{IH}$ High-level input voltage	2		2		V
$V_{IL}$ Low-level input voltage		0.8		0.8	V
$V_I$ Input voltage	0	5.5	0	5.5	V
$V_O$ Output voltage	0	$V_{CC}$	0	$V_{CC}$	V
$I_{OH}$ High-level output current		–8		–8	mA
$I_{OL}$ Low-level output current		8		8	mA
$\Delta t/\Delta v$ Input transition rise or fall rate		20		20	ns/V
$T_A$ Operating free-air temperature	–55	125	–40	85	°C

NOTE 4: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



# SN54AHCT125, SN74AHCT125 QUADRUPLE BUS BUFFER GATES WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54AHCT125		SN74AHCT125		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = -50 μA	4.5 V	4.4	4.5		4.4		4.4	V	
	I <sub>OH</sub> = -8 mA		3.94			3.8		3.8		
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	4.5 V			0.1			0.1	V	
	I <sub>OL</sub> = 8 mA				0.36		0.44	0.44		
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	0 V to 5.5 V			±0.1			±1	μA	
I <sub>OZ</sub>	V <sub>O</sub> = V <sub>CC</sub> or GND	5.5 V			±0.25			±2.5	μA	
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V			2		20	20	μA	
ΔI <sub>CC</sub> †	One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	5.5 V			1.35		1.5	1.5	mA	
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		4	10			10	pF	
C <sub>o</sub>	V <sub>O</sub> = V <sub>CC</sub> or GND	5 V		15					pF	

\* On products compliant to MIL-PRF-38535, this parameter is not production tested at V<sub>CC</sub> = 0 V.

† This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V<sub>CC</sub>.

switching characteristics over recommended operating free-air temperature range, V<sub>CC</sub> = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T <sub>A</sub> = 25°C			SN54AHCT125		SN74AHCT125		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A	Y	C <sub>L</sub> = 15 pF		3.8**	5.5**	1**	6.5**	1	6.5	ns
t <sub>PHL</sub>				3.8**	5.5**	1**	6.5**	1	6.5		
t <sub>PZH</sub>	OE	Y	C <sub>L</sub> = 15 pF		3.6**	5.1**	1**	6**	1	6	ns
t <sub>PZL</sub>				3.6**	5.1**	1**	6**	1	6		
t <sub>PHZ</sub>	OE	Y	C <sub>L</sub> = 15 pF		4.6**	6.8**	1**	8**	1	8	ns
t <sub>PLZ</sub>				4.6**	6.8**	1**	8**	1	8		
t <sub>PLH</sub>	A	Y	C <sub>L</sub> = 50 pF		5.3	7.5	1	8.5	1	8.5	ns
t <sub>PHL</sub>				5.3	7.5	1	8.5	1	8.5		
t <sub>PZH</sub>	OE	Y	C <sub>L</sub> = 50 pF		5.1	7.1	1	8	1	8	ns
t <sub>PZL</sub>				5.1	7.1	1	8	1	8		
t <sub>PHZ</sub>	OE	Y	C <sub>L</sub> = 50 pF		6.1	8.8	1	10	1	10	ns
t <sub>PLZ</sub>				6.1	8.8	1	10	1	10		
t <sub>sk(o)</sub>			C <sub>L</sub> = 50 pF			1***			1	ns	

\*\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

\*\*\* On products compliant to MIL-PRF-38535, this parameter does not apply.

noise characteristics, V<sub>CC</sub> = 5 V, C<sub>L</sub> = 50 pF, T<sub>A</sub> = 25°C (see Note 5)

PARAMETER	SN74AHCT125		UNIT
	MIN	MAX	
V <sub>OL(P)</sub> Quiet output, maximum dynamic V <sub>OL</sub>		0.8	V
V <sub>OL(V)</sub> Quiet output, minimum dynamic V <sub>OL</sub>		-0.8	V
V <sub>OH(V)</sub> Quiet output, minimum dynamic V <sub>OH</sub>	4.4		V
V <sub>IH(D)</sub> High-level dynamic input voltage	2		V
V <sub>IL(D)</sub> Low-level dynamic input voltage		0.8	V

NOTE 5: Characteristics are for surface-mount packages only.



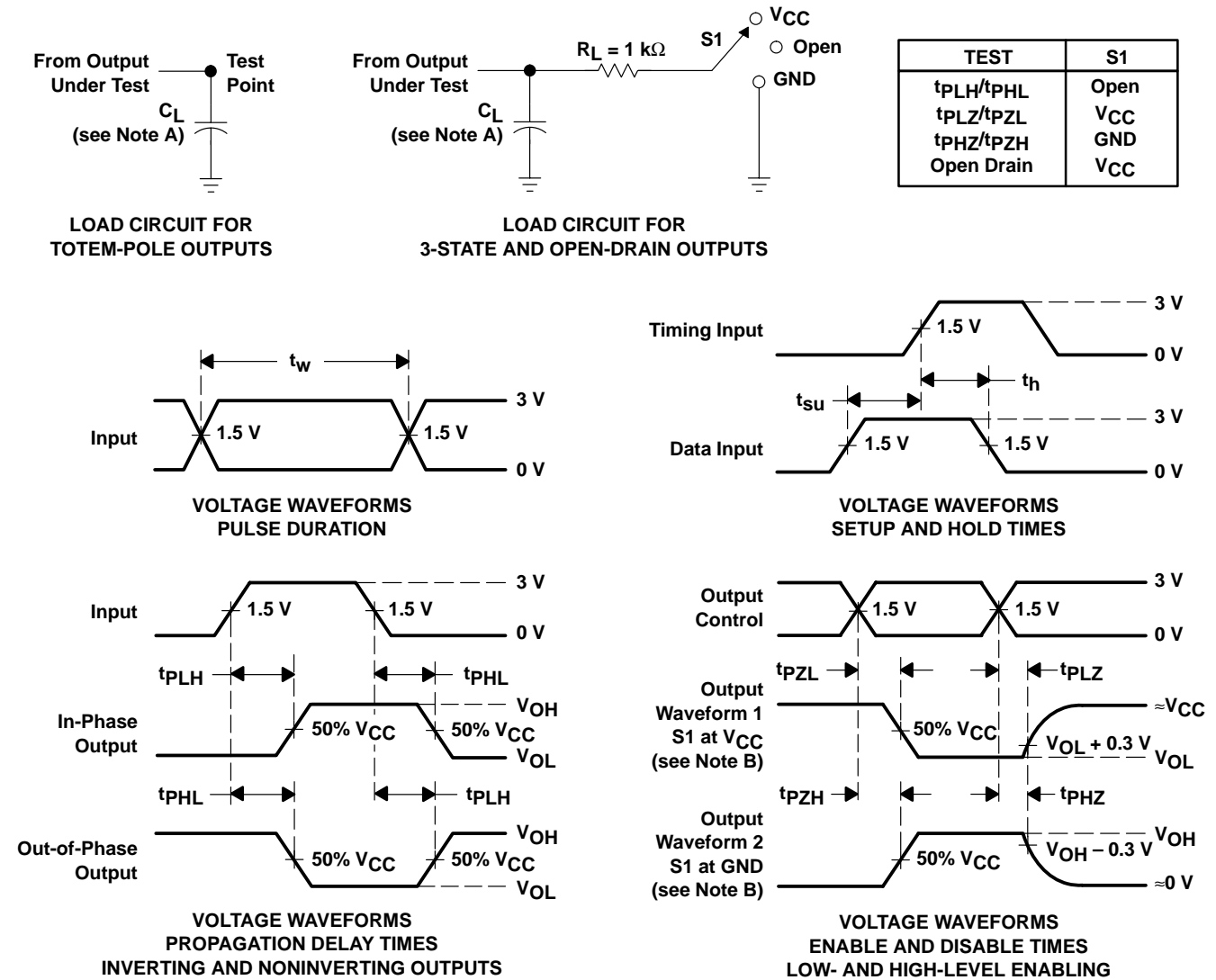
# SN54AHCT125, SN74AHCT125 QUADRUPLE BUS BUFFER GATES WITH 3-STATE OUTPUTS

SCLS2640 – DECEMBER 1995 – REVISED JULY 2003

operating characteristics,  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
$C_{pd}$ Power dissipation capacitance	No load, $f = 1\text{ MHz}$	14	pF

## PARAMETER MEASUREMENT INFORMATION



- NOTES:
- $C_L$  includes probe and jig capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 3\text{ ns}$ ,  $t_f \leq 3\text{ ns}$ .
  - The outputs are measured one at a time with one input transition per measurement.
  - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-9686901Q2A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
5962-9686901QCA	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
5962-9686901QDA	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
SN74AHCT125D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74AHCT125DBLE	OBSOLETE	SSOP	DB	14		None	Call TI	Call TI
SN74AHCT125DBR	ACTIVE	SSOP	DB	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74AHCT125DGVR	ACTIVE	TVSOP	DGV	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74AHCT125DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74AHCT125N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74AHCT125NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74AHCT125PW	ACTIVE	TSSOP	PW	14	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74AHCT125PWLE	OBSOLETE	TSSOP	PW	14		None	Call TI	Call TI
SN74AHCT125PWR	ACTIVE	TSSOP	PW	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74AHCT125RGYR	ACTIVE	QFN	RGY	14	1000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR
SNJ54AHCT125FK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54AHCT125J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SNJ54AHCT125W	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - May not be currently available - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**None:** Not yet available Lead (Pb-Free).

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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# J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



4040140/D 10/96

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.
  - E. Falls within JEDEC MS-004



DGV (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194

D (R-PDSO-G14)

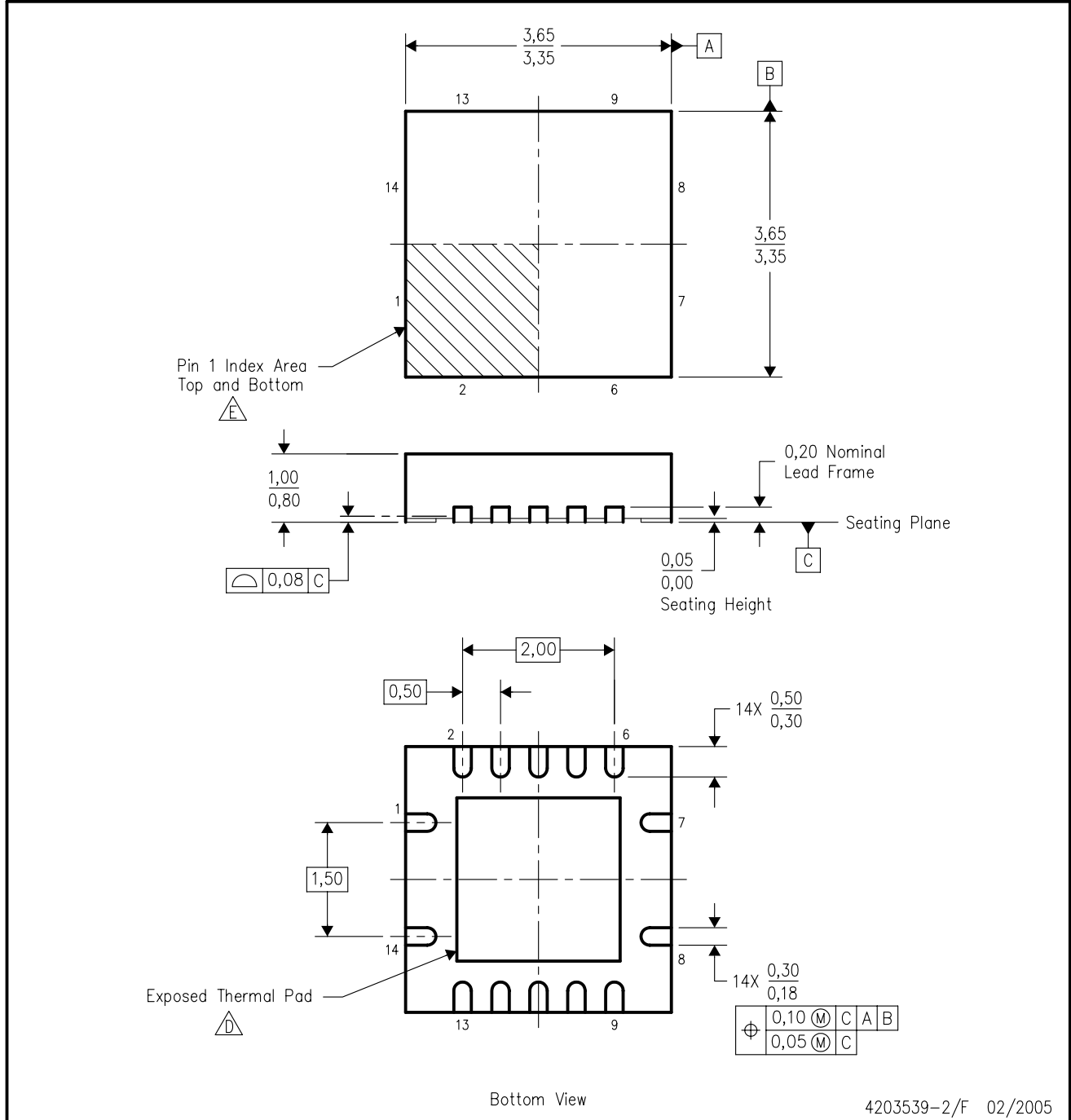
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-012 variation AB.

RGY (S-PQFP-N14)

PLASTIC QUAD FLATPACK



4203539-2/F 02/2005

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. QFN (Quad Flatpack No-Lead) package configuration.
  - The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.
  - Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
  - F. Package complies to JEDEC MO-241 variation BA.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

PW (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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